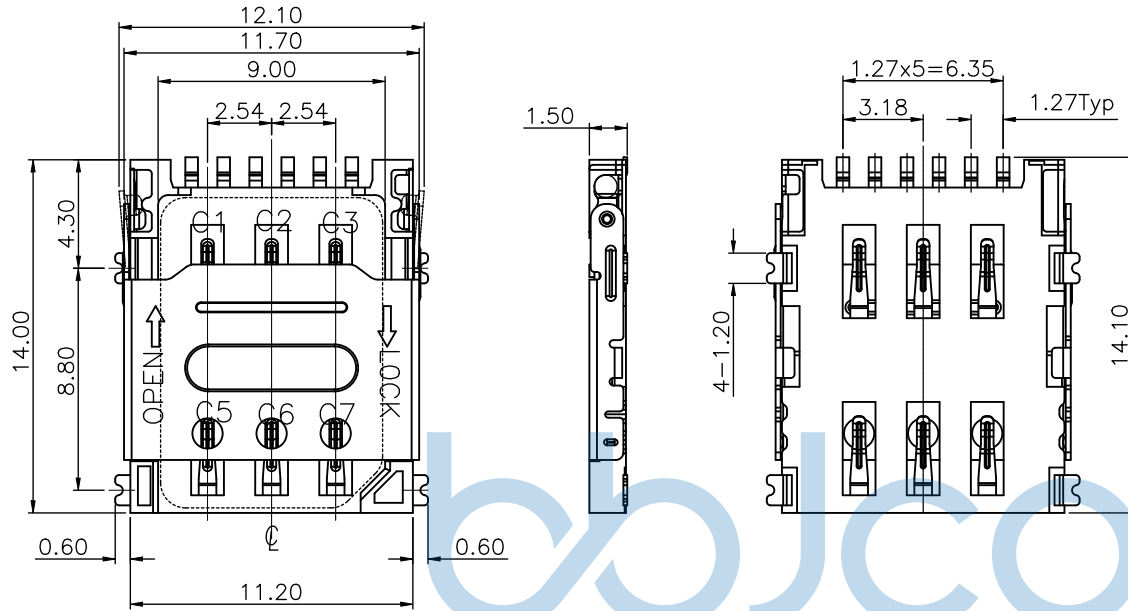


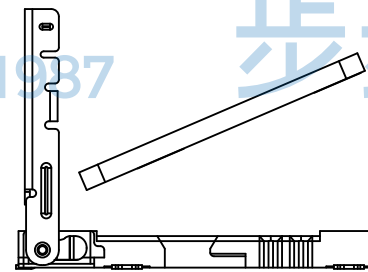
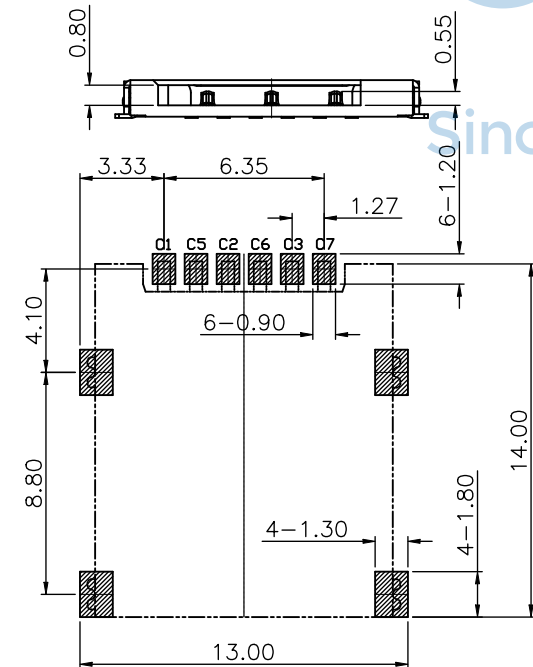
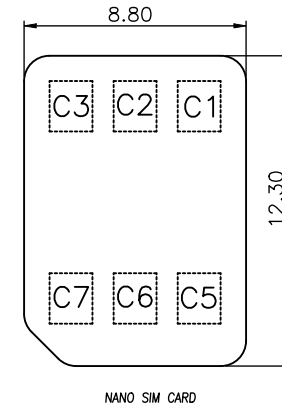
REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



NOTES:

- ELECTRICAL CHARACTERISTICS
  - CONTACT RESISTANCE: 60 Milliohms Max
  - INSULATION RESISTANCE: 1,000 Megohms Min.
  - VOLTAGE RATING: 50V.
  - CURRENT RATING: 1.0A.
- MECHANICAL CHARACTERISTICS
  - OPERATION TEMPERATURE RANGE: -20°C~+85°C
  - DURABILITY: 5000 CYCLES
- MATERIAL:
  - HOUSING: THERMOPLASTIC,UL 94-V0
  - TERMINAL: PHOSPHOR BRONZE,T=0.15
  - SHELL: STAINLESS STEEL,T=0.20
- FINISHED:
  - TERMINAL: Ni PLATED UNDER, 3U" Au MIN PLATED ON CONTACT AREA,AU PLATED ON SOLDER TAIL

Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



STEP 1 INSERT Micro-SIM CARD

STEP 2 PUSH THE SHELL

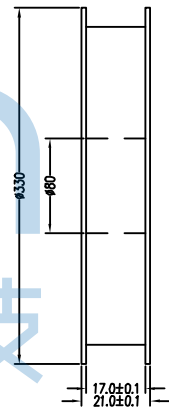
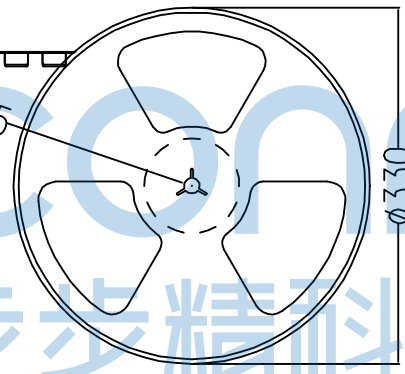
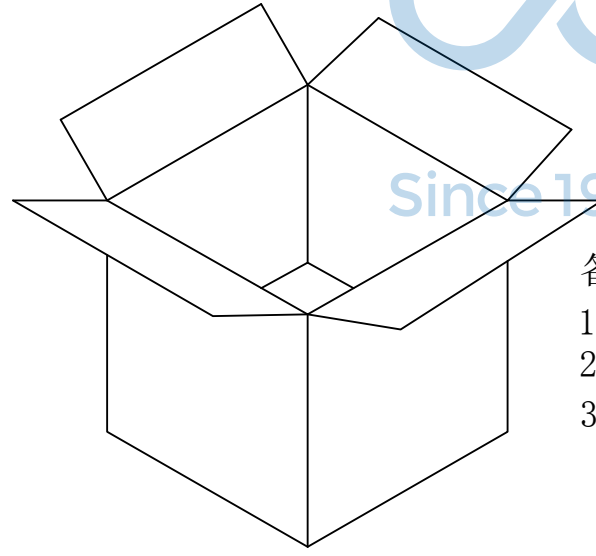
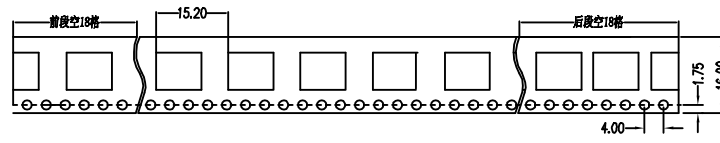
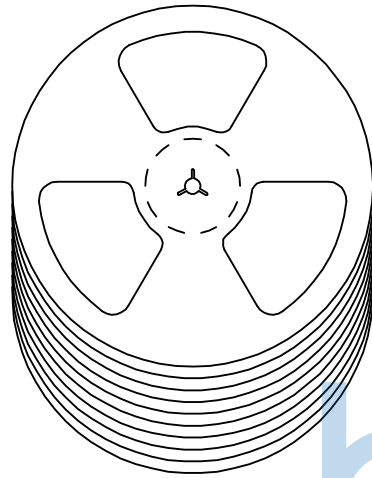
STEP 3 FINISH

RECOMMENDED PCB LAYOUT  
GENERAY TOLERANCE ±0.05



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PDWG.NO: 0214-1	DR. TSP	NAME: 卡座 NANO SIM 6P 掀盖式 H=1.5 贴片 无柱 编带	PJ. NO.: CD.02.02-02-0014 SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



备注:

1. 包装数量: 1500/PCS/卷, 10卷/箱。
2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
3. 材质:  
载体: 聚丙烯 (PS),  
上带: 聚乙烯 (PET),  
卷盘: 聚苯乙烯。

纸箱规格: 345\*345\*23MM  
纸箱规格: 345\*345\*35MM

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APPD.	JM_Zheng				
CHKD.	LYX				
PDWG.NO:	0214-1	DR.	TSP		